

N-Channel MOSFET

Automotive Dual N-Channel 30 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	30			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.007			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0086			
I _D (A) per leg	30			
Configuration	Dual			

PowerPAK® SO-8L Dual

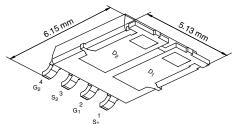
FEATURES

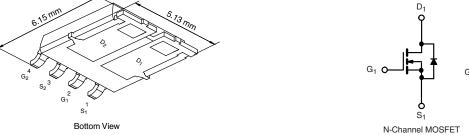
- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested
- AEC-Q101 Qualifiedd
- · Material categorization: For definitions of compliance please see www.vishay.com/doc?99912





RoHS COMPLIANT HALOGEN **FREE**





ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SQJ910AEP-T1-GE3

ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unles	s otherwise noted	d)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Currenta	T _C = 25 °C	1	30		
Continuous Drain Current	T _C = 125 °C	I _D	30		
Continuous Source Current (Diode Conduction) ^a		Is	30	Α	
Pulsed Drain Current ^b		I _{DM}	120		
Single Pulse Avalanche Current L = 0.1 mH		I _{AS}	29		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	42	mJ	
Maximum Bayyar Dissinationh	T _C = 25 °C	В	48	W	
Maximum Power Dissipation ^b	T _C = 125 °C	P_{D}	16	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)e, f			260	C	

THERMAL RESISIANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	85	°C/W
Junction-to-Case (Drain)		R_{thJC}	3.1	C/VV

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.
- e. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	1					L	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	1.5	2	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	$0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 30 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 30 V, T _J = 125 °C	-	-	50	μΑ
		V _{GS} = 0 V	V _{DS} = 30 V, T _J = 175 °C	-	-	150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V _{GS} = 10 V	I _D = 12 A	-	0.0058	0.007	Ω
Drain Course On State Besistance		V _{GS} = 4.5 V	I _D = 10.7 A	=.	0.0072	0.0086	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 12 A, T _J = 125 °C	-	-	0.0096	
		V _{GS} = 10 V	I _D = 12 A, T _J = 175 °C	-	-	0.012	
Forward Transconductance ^b	9 _{fs}	V_{DS}	= 15 V, I _D = 12 A	-	72	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			=-	1495	1869	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	=.	313	391	рF
Reverse Transfer Capacitance	C _{rss}			-	126	158	
Total Gate Charge ^c	Qg			-	25.8	39	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 15 \text{ V}, I_{D} = 11.3 \text{ A}$	-	4.3	-	nC
Gate-Drain Charge ^c	Q _{gd}			-	4.3	-	
Gate Resistance	R _g		f = 1 MHz	0.6	1.38	2.10	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	11	16	
Rise Time ^c	t _r	V _{DD} =	= 15 V, R _L = 1.4 Ω	-	3	4	
Turn-Off Delay Time ^c	t _{d(off)}	I _D ≅ 1 Å, '	$V_{\text{GEN}} = 10 \text{ V}, R_{\text{g}} = 1 \Omega$	-	27	40	ns
Fall Time ^c	t _f	1		-	7	11	
Source-Drain Diode Ratings and Chara	acteristics ^b						
Pulsed Current ^a	I _{SM}			-	-	120	Α
	0	I _F = 7.8 A, V _{GS} = 0 V					

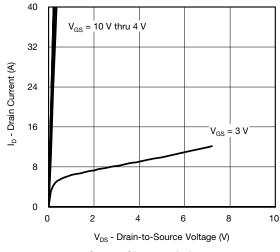
Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

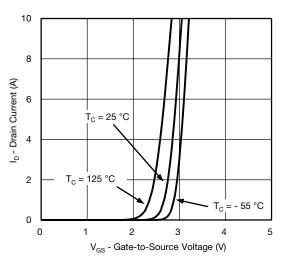
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



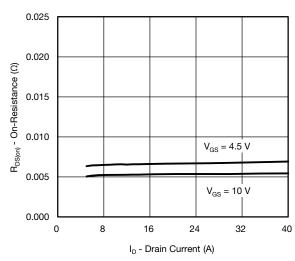
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



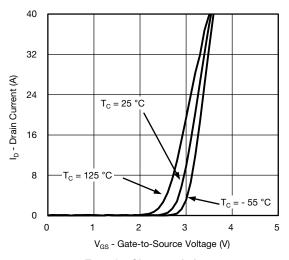
Output Characteristics



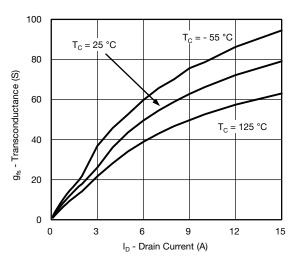
Transfer Characteristics



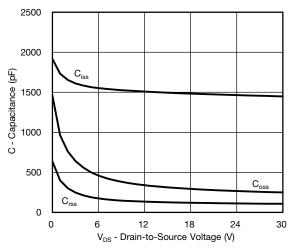
On-Resistance vs. Drain Current



Transfer Characteristics



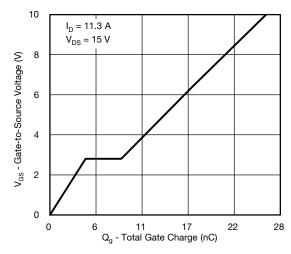
Transconductance



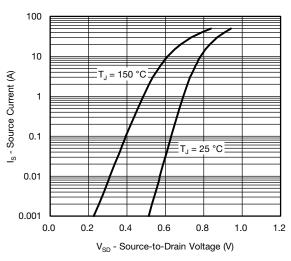
Capacitance



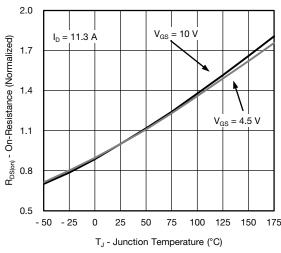
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



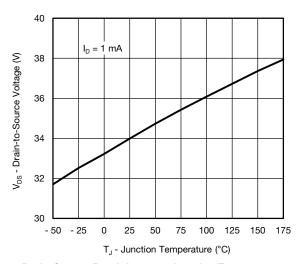
Gate Charge



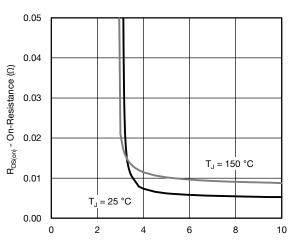
Source Drain Diode Forward Voltage



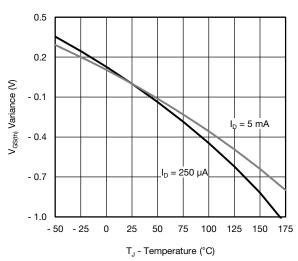
On-Resistance vs. Junction Temperature



Drain-Source Breakdown vs. Junction Temperature

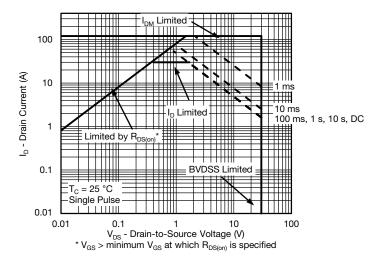


 $\label{eq:VGS} V_{GS} \mbox{ - Gate-to-Source Voltage (V)}$ $\mbox{On-Resistance vs. Gate-to-Source Voltage}$

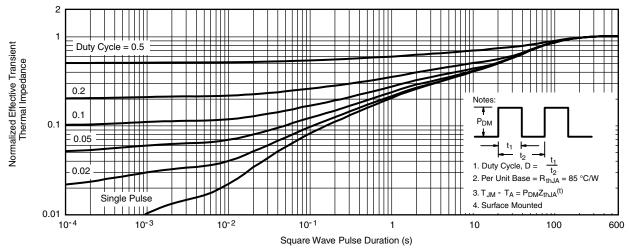


Threshold Voltage

THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



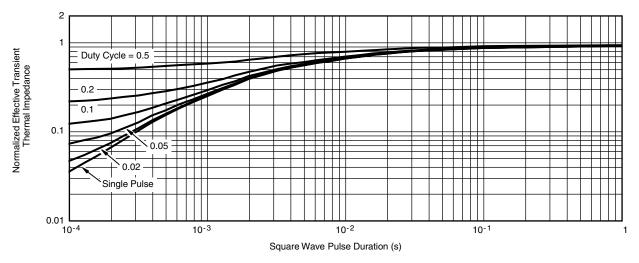
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

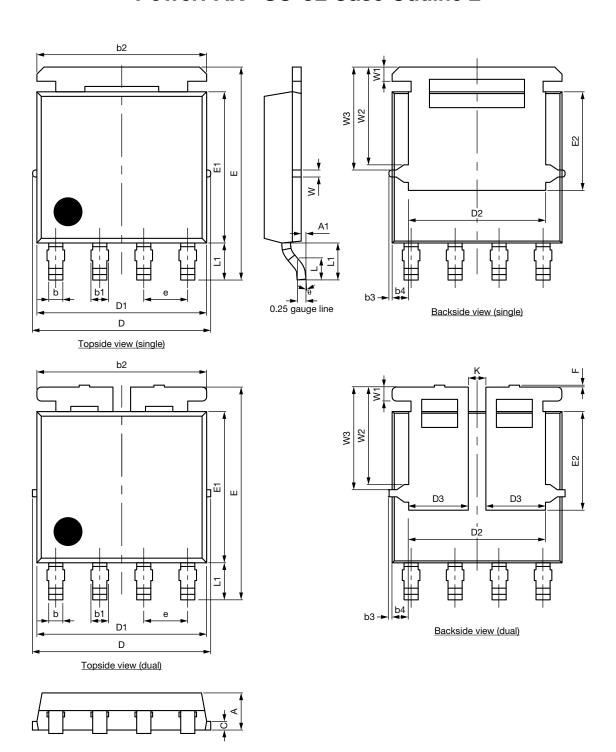
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63748.



PowerPAK® SO-8L Case Outline 2



DIM.		MILLIMETERS			INCHES			
DIN.	MIN.	NOM.	MAX.	MIN.	NOM.	M. MAX.		
А	1.00	1.07	1.14	0.039	0.042	0.045		
A1	0.00	-	0.127	0.00	-	0.005		
b	0.33	0.41	0.48	0.013	0.016	0.019		
b1	0.44	0.51	0.58	0.017	0.020	0.023		
b2	4.80	4.90	5.00	0.189	0.193	0.197		
b3		0.094			0.004	•		
b4		0.47			0.019			
С	0.20	0.25	0.30	0.008	0.010	0.012		
D	5.00	5.13	5.25	0.197	0.202	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D3	1.63	1.73	1.83	0.064	0.068	0.072		
е		1.27 BSC		0.050 BSC				
Е	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	2.75	2.85	2.95	0.108	0.112	0.116		
F	-	-	0.15	-	-	0.006		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
K		0.51			0.020			
W		0.23		0.009				
W1	0.41		0.016					
W2	2.82			0.111				
W3		2.96			0.117			
θ	0°	-	10°	0°	-	10°		

ECN: C21-1498-Rev. C, 01-Nov-2021

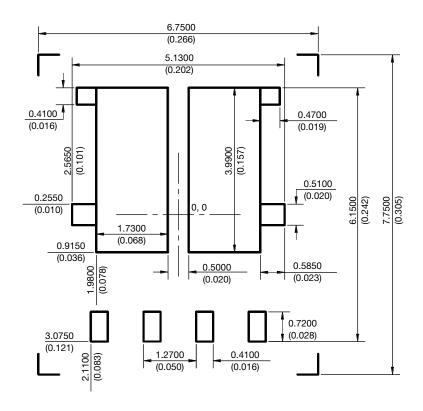
DWG: 6044

Note

• Millimeters will govern



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL



Recommended Minimum Pads Dimensions in mm (inches) Keep-out 6.75 (0.266) x 7.75 (0.305)



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